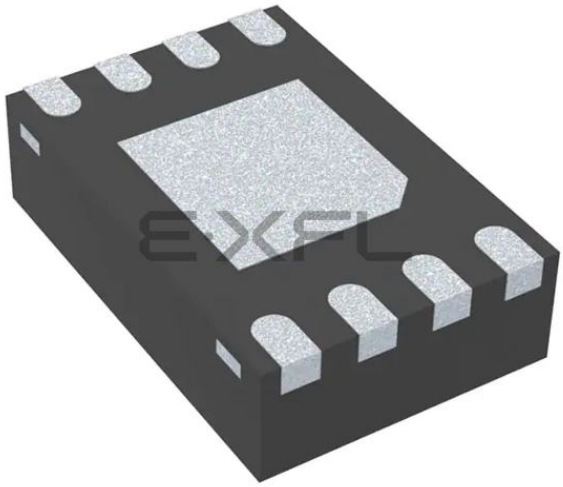

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	4
Program Memory Size	768B (512 x 12)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	23 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VFDFN Exposed Pad
Supplier Device Package	8-DFN (2x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic10f222-i-mc

NOTES:

TABLE 4-1: SPECIAL FUNCTION REGISTER (SFR) SUMMARY

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset(2)	Page #
00h	INDF	Uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	20
01h	TMR0	8-Bit Real-Time Clock/Counter								xxxx xxxx	25
02h	PCL(1)	Low Order 8 Bits of PC								1111 1111	19
03h	STATUS	GPWUF	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0--1 1xxx(3)	15
04h	FSR	Indirect Data Memory Address Pointer								111x xxxx	20
05h	OSCCAL	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	FOSC4	1111 1110	18
06h	GPIO	—	—	—	—	GP3	GP2	GP1	GP0	---- xxxx	21
07h	ADCON0	ANS1	ANS0	—	—	CHS1	CHS0	GO/$\overline{DONE}$	ADON	11-- 1100	30
08h	ADRES	Result of Analog-to-Digital Conversion								xxxx xxxx	31
N/A	TRISGPIO	—	—	—	—	I/O Control Register				---- 1111	23
N/A	OPTION	$\overline{GPWU}$	$\overline{GPPU}$	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	17

Legend: – = unimplemented, read as '0', x = unknown, u = unchanged, q = value depends on condition.

Note 1: The upper byte of the Program Counter is not directly accessible. See **Section 4.7 "Program Counter"** for an explanation of how to access these bits.

2: Other (non Power-up) Resets include external Reset through $\overline{MCLR}$, Watchdog Timer and wake-up on pin change Reset.

3: See Table 8-1 for other Reset specific values.

4.4 STATUS Register

This register contains the arithmetic status of the ALU, the Reset status and the page preselect bit.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper three bits and set the Z bit. This leaves the STATUS register as `000u u1uu` (where `u` = unchanged).

Therefore, it is recommended that only `BCF`, `BSF` and `MOVWF` instructions be used to alter the STATUS register. These instructions do not affect the Z, DC or C bits from the STATUS register. For other instructions, which do affect Status bits, see Instruction Set Summary.

7.9 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 7-1. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), see Figure 7-1. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 7-1 may be used. This equation assumes that 1/2 LSb error is used (256 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 7-1: ACQUISITION TIME EXAMPLE

Assumptions:

Temperature = 50°C and external impedance of 10 kΩ 5.0V VDD

Tacq = Amplifier Settling Time + Hold Capacitor Charging Time + Temperature Coefficient

= TAMP + TC + TCOFF

= 2 μs + TC + [(Temperature - 25°C)(0.05 μs/°C)]

Solving for Tc:

Tc = CHOLD (RIC + RSS + RS) In(1/512)

= -25pF (l kΩ + 7 kΩ + 10 kΩ) In(0.00196)

= 2.81 μs

Therefore:

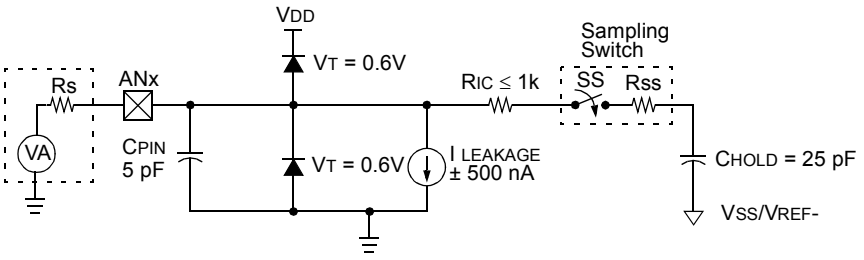
Tacq = 2 μs + 2.81 μs + [(50°C-25°C)(0.0 5μs/°C)]

= 6.06 μs

Note 1: The charge holding capacitor (CHOLD) is not discharged after each conversion.

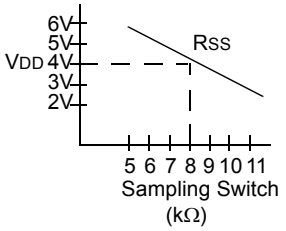
2: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

FIGURE 7-1: ANALOG INPUT MODULE



Legend:

CPIN	=	Input Capacitance
VT	=	Threshold Voltage
ILEAKAGE	=	Leakage current at the pin due to various junctions
RIC	=	Interconnect Resistance
SS	=	Sampling Switch
CHOLD	=	Sample/Hold Capacitance



8.0 SPECIAL FEATURES OF THE CPU

What sets a microcontroller apart from other processors are special circuits that deal with the needs of real-time applications. The PIC10F220/222 microcontrollers have a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power-saving operating modes and offer code protection. These features are:

- Reset:
  - Power-on Reset (POR)
  - Device Reset Timer (DRT)
  - Watchdog Timer (WDT)
  - Wake-up from Sleep on pin change
- Sleep
- Code Protection
- ID Locations
- In-Circuit Serial Programming™
- Clock Out

The PIC10F220/222 devices have a Watchdog Timer, which can be shut off only through Configuration bit WDTE. It runs off of its own RC oscillator for added reliability. When using DRT, there is an 1.125 ms (typical) delay only on VDD power-up. With this timer on-chip, most applications need no external Reset circuitry.

The Sleep mode is designed to offer a very low current Power-Down mode. The user can wake-up from Sleep through a change on input pins or through a Watchdog Timer time-out.

8.1 Configuration Bits

The PIC10F220/222 Configuration Words consist of 12 bits. Configuration bits can be programmed to select various device configurations. One bit is the Watchdog Timer enable bit, one bit is the $\overline{\text{MCLR}}$ enable bit and one bit is for code protection (see Register 8-1).

REGISTER 8-1: CONFIG: CONFIGURATION WORD(1)

—	—	—	—	—	—	—	MCLRE	$\overline{\text{CP}}$	WDTE	$\overline{\text{MCPU}}$	IOSCFS
bit 11											bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 11-5 **Unimplemented:** Read as '0'

bit 4 **MCLRE:** GP3/$\overline{\text{MCLR}}$ Pin Function Select bit
1 = GP3/$\overline{\text{MCLR}}$ pin function is $\overline{\text{MCLR}}$
0 = GP3/$\overline{\text{MCLR}}$ pin function is digital I/O, $\overline{\text{MCLR}}$ internally tied to VDD

bit 3 **$\overline{\text{CP}}$:** Code Protection bit
1 = Code protection off
0 = Code protection on

bit 2 **WDTE:** Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1 **$\overline{\text{MCPU}}$:** Master Clear Pull-up Enable bit(2)
1 = Pull-up disabled
0 = Pull-up enabled

bit 0 **IOSCFS:** Internal Oscillator Frequency Select bit
1 = 8 MHz
0 = 4 MHz

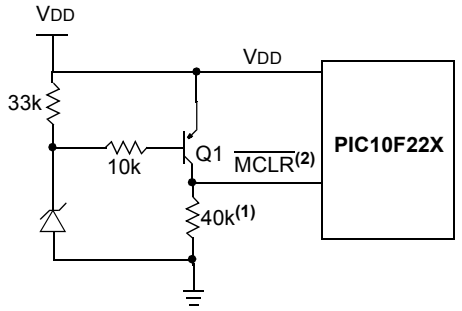
Note 1: Refer to the "*PIC10F220/222 Memory Programming Specification*" (DS41266), to determine how to access the Configuration Word. The Configuration Word is not user addressable during device operation.
2: MCLRE must be a '1' to enable this selection.

8.8 Reset on Brown-out

A Brown-out is a condition where device power (VDD) dips below its minimum value, but not to zero, and then recovers. The device should be reset in the event of a Brown-out.

To reset PIC10F220/222 devices when a Brown-out occurs, external Brown-out protection circuits may be built, as shown in Figure 8-7 and Figure 8-8.

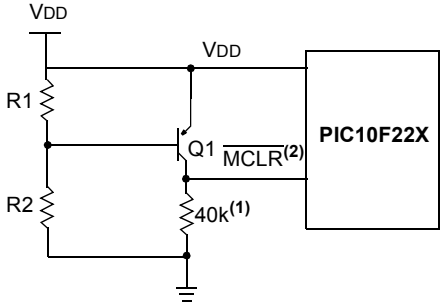
FIGURE 8-7: BROWN-OUT PROTECTION CIRCUIT 1



Note 1: This circuit will activate Reset when VDD goes below Vz + 0.7V (where Vz = Zener voltage).

2: Pin must be configured as $\overline{MCLR}$.

FIGURE 8-8: BROWN-OUT PROTECTION CIRCUIT 2

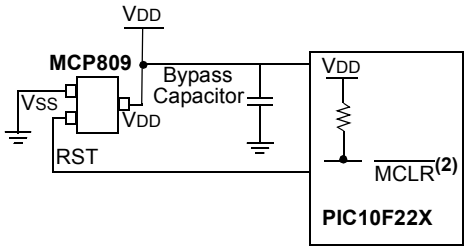


Note 1: This brown-out circuit is less expensive, although less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \cdot \frac{R1}{R1 + R2} = 0.7V$$

2: Pin must be configured as $\overline{MCLR}$.

FIGURE 8-9: BROWN-OUT PROTECTION CIRCUIT 3



Note 1: This Brown-out Protection circuit employs Microchip Technology's MCP809 micro-controller supervisor. There are 7 different trip point selections to accommodate 5V to 3V systems.

2: Pin must be configured as $\overline{MCLR}$.

8.9 Power-down Mode (Sleep)

A device may be powered down (Sleep) and later powered up (wake-up from Sleep).

8.9.1 SLEEP

The Power-Down mode is entered by executing a `SLEEP` instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the $\overline{TO}$ bit (STATUS<4>) is set, the $\overline{PD}$ bit (STATUS<3>) is cleared and the oscillator driver is turned off. The I/O ports maintain the status they had before the `SLEEP` instruction was executed (driving high, driving low or high-impedance).

Note: A Reset generated by a WDT time-out does not drive the $\overline{MCLR}$ pin low.

For lowest current consumption while powered down, the T0CKI input should be at VDD or VSS and the GP3/$\overline{MCLR}$/VPP pin must be at a logic high level if $\overline{MCLR}$ is enabled.

8.9.2 WAKE-UP FROM SLEEP

The device can wake-up from Sleep through one of the following events:

1. An external Reset input on GP3/MCLR/VPP pin, when configured as MCLR.
2. A Watchdog Timer Time-out Reset (if WDT was enabled).
3. A change on input pin GP0, GP1 or GP3 when wake-up on change is enabled.

These events cause a device Reset. The TO, PD GPWUF bits can be used to determine the cause of a device Reset. The TO bit is cleared if a WDT time-out occurred (and caused wake-up). The PD bit, which is set on power-up, is cleared when SLEEP is invoked. The GPWUF bit indicates a change in state while in Sleep at pins GP0, GP1 or GP3 (since the last file or bit operation on GP port).

Caution:	Right before entering Sleep, read the input pins. When in Sleep, wake up occurs when the values at the pins change from the state they were in at the last reading. If a wake-up on change occurs and the pins are not read before re-entering Sleep, a wake-up will occur immediately even if no pins change while in Sleep mode.

Note:	The WDT is cleared when the device wakes from Sleep, regardless of the wake-up source.

8.10 Program Verification/Code Protection

If the Code Protection bit has not been programmed, the on-chip program memory can be read out for verification purposes.

The first 64 locations and the last location (Reset Vector) can be read, regardless of the code protection bit setting.

8.11 ID Locations

Four memory locations are designated as ID locations where the user can store checksum or other code identification numbers. These locations are not accessible during normal execution, but are readable and writable during program/verify.

Use only the lower 4 bits of the ID locations and always program the upper 8 bits as '1's.

8.12 In-Circuit Serial Programming™

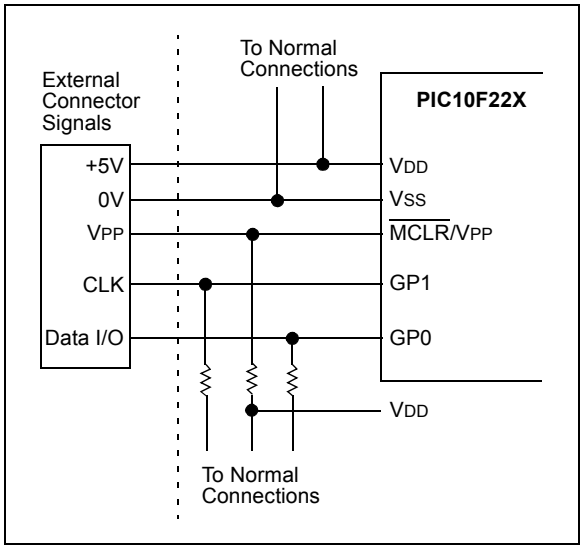
The PIC10F220/222 microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware, or a custom firmware, to be programmed.

The devices are placed into a Program/Verify mode by holding the GP1 and GP0 pins low while raising the MCLR (VPP) pin from VIL to VIHH (see programming specification). GP1 becomes the programming clock and GP0 becomes the programming data. Both GP1 and GP0 are Schmitt Trigger inputs in this mode.

After Reset, a 6-bit command is then supplied to the device. Depending on the command, 16 bits of program data are then supplied to or from the device, depending if the command was a Load or a Read. For complete details of serial programming, please refer to the PIC10F220/222 Programming Specifications.

A typical In-Circuit Serial Programming connection is shown in Figure 8-10.

FIGURE 8-10: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING™ CONNECTION



9.0 INSTRUCTION SET SUMMARY

The PIC16 instruction set is highly orthogonal and is comprised of three basic categories.

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

Each PIC16 instruction is a 12-bit word divided into an **opcode**, which specifies the instruction type, and one or more **operands** which further specify the operation of the instruction. The formats for each of the categories is presented in Figure 9-1, while the various opcode fields are summarized in Table 9-1.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8 or 9-bit constant or literal value.

TABLE 9-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0 (store result in W) d = 1 (store result in file register 'f') Default is d = 1
label	Label name
TOS	Top-of-Stack
PC	Program Counter
WDT	Watchdog Timer counter
$\overline{TO}$	Time-out bit
$\overline{PD}$	Power-down bit
dest	Destination, either the W register or the specified register file location
[ ]	Options
( )	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
italics	User defined term (font is courier)

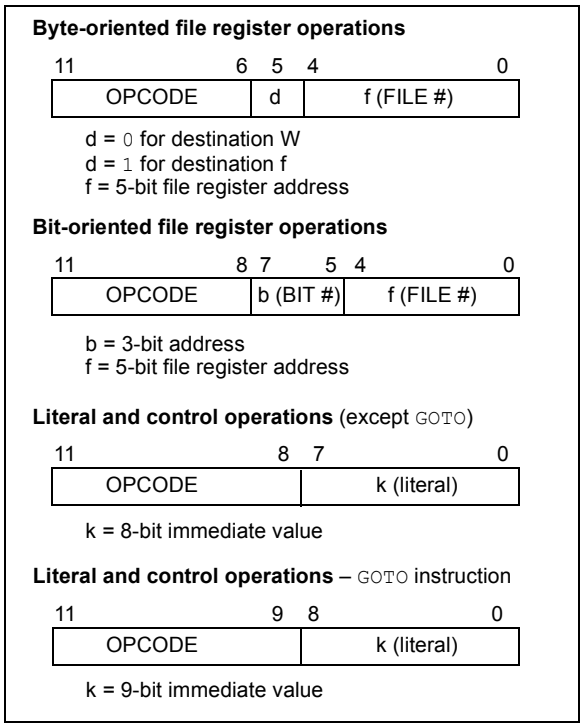
All instructions are executed within a single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Figure 9-1 shows the three general formats that the instructions can have. All examples in the figure use the following format to represent a hexadecimal number:

'0xhhh'

where 'h' signifies a hexadecimal digit.

FIGURE 9-1: GENERAL FORMAT FOR INSTRUCTIONS



BTFSS	Bit Test f, Skip if Set
Syntax:	[*label*] BTFSS f,b
Operands:	$0 \le f \le 31$ $0 \le b < 7$
Operation:	skip if (f<b>) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' is '1', then the next instruction is skipped. If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and a NOP is executed instead, making this a two-cycle instruction.

CALL	Subroutine Call
Syntax:	[*label*] CALL k
Operands:	$0 \le k \le 255$
Operation:	(PC) + 1→ Top of Stack; k → PC<7:0>; (Status<6:5>) → PC<10:9>; 0 → PC<8>
Status Affected:	None
Description:	Subroutine call. First, return address (PC + 1) is pushed onto the stack. The eight-bit immediate address is loaded into PC bits <7:0>. The upper bits PC<10:9> are loaded from STATUS<6:5>, PC<8> is cleared. CALL is a two-cycle instruction.

CLRF	Clear f
Syntax:	[*label*] CLRF f
Operands:	$0 \le f \le 31$
Operation:	00h → (f); 1 → Z
Status Affected:	Z
Description:	The contents of register 'f' are cleared and the Z bit is set.

CLRW	Clear W
Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W); 1 → Z
Status Affected:	Z
Description:	The W register is cleared. Zero bit (Z) is set.

CLRWDT	Clear Watchdog Timer
Syntax:	[*label*] CLRWDT k
Operands:	None
Operation:	00h → WDT; 0 → WDT prescaler (if assigned); 1 → $\overline{TO}$; 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	The CLRWDT instruction resets the WDT. It also resets the prescaler, if the prescaler is assigned to the WDT and not Timer0. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF	Complement f
Syntax:	[*label*] COMF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	$(\bar{f}) \rightarrow$ (dest)
Status Affected:	Z
Description:	The contents of register 'f' are complemented. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

10.3 DC Characteristics: PIC10F220/222 (Industrial, Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating temperature -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended) Operating voltage VDD range as described in DC specification				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O ports:					
D030		with TTL buffer	Vss	—	0.8	V	For all 4.5 ≤ VDD ≤ 5.5V
D030A			Vss	—	0.15 VDD	V	Otherwise
D031		with Schmitt Trigger buffer	Vss	—	0.2 VDD	V	
D032		$\overline{MCLR}$, T0CKI	Vss	—	0.2 VDD	V	
	VIH	**Input High Voltage**					
		I/O ports:		—			
D040		with TTL buffer	2.0	—	VDD	V	4.5 ≤ VDD ≤ 5.5V
D040A			0.25 VDD + 0.8	—	VDD	V	Otherwise
D041		with Schmitt Trigger buffer	0.8VDD	—	VDD	V	For entire VDD range
D042		$\overline{MCLR}$, T0CKI	0.8VDD	—	VDD	V	
D070	IPUR	**GPIO weak pull-up current**	50	250	400	µA	VDD = 5V, VPIN = VSS
	IIL	**Input Leakage Current(1)**					
D060		I/O ports	—	±0.1	± 1	µA	Vss ≤ VPIN ≤ VDD, Pin at high-impedance
D061		GP3/$\overline{MCLR}$(2)	—	±0.7	± 5	µA	Vss ≤ VPIN ≤ VDD
		Output Low Voltage					
D080		I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
D080A			—	—	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C
		Output High Voltage					
D090		I/O ports(2)	VDD – 0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
D090A			VDD – 0.7	—	—	V	IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C
		Capacitive Loading Specs on Output Pins					
D101		All I/O pins	—	—	50*	pF	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

* These parameters are for design guidance only and are not tested.

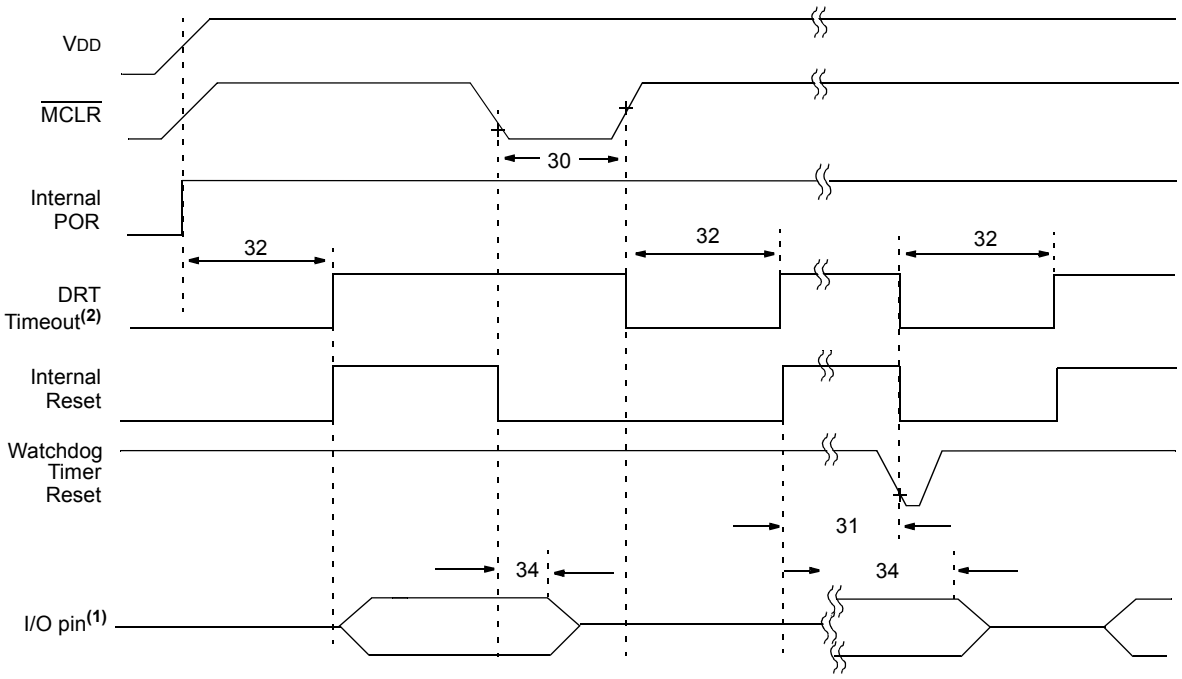
Note 1: Negative current is defined as coming out of the pin.

2: This specification applies when GP3/$\overline{MCLR}$ is configured as an input with pull-up disabled. The leakage current of the $\overline{MCLR}$ circuit is higher than the standard I/O logic.

TABLE 10-1: PULL-UP RESISTOR RANGES

VDD (Volts)	Temperature (°C)	Min	Typ	Max	Units
GP0/GP1					
2.0	-40	73K	105K	186K	Ω
	25	73K	113K	187K	Ω
	85	82K	123K	190K	Ω
	125	86K	132k	190K	Ω
5.5	-40	15K	21K	33K	Ω
	25	15K	22K	34K	Ω
	85	19K	26k	35K	Ω
	125	23K	29K	35K	Ω
GP3					
2.0	-40	63K	81K	96K	Ω
	25	77K	93K	116K	Ω
	85	82K	96k	116K	Ω
	125	86K	100K	119K	Ω
5.5	-40	16K	20k	22K	Ω
	25	16K	21K	23K	Ω
	85	24K	25k	28K	Ω
	125	26K	27K	29K	Ω

FIGURE 10-3: RESET, WATCHDOG TIMER AND DEVICE RESET TIMER TIMING



Note 1: I/O pins must be taken out of High-impedance mode by enabling the output drivers in software.
2: Runs on POR Reset only.

TABLE 10-3: RESET, WATCHDOG TIMER AND DEVICE RESET TIMER – PIC10F220/222

AC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended) Operating Voltage VDD range is described in **Section 10.1 "DC Characteristics: PIC10F220/222 (Industrial)"**				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
30	T_{MCL}	$\overline{MCLR}$ Pulse Width (low)	2* 5*	— —	— —	µs µs	VDD = 5V, -40°C to +85°C VDD = 5.0V
31	TWDT	Watchdog Timer Time-out Period (no prescaler)	10 10	18 18	29 31	ms ms	VDD = 5.0V (Industrial) VDD = 5.0V (Extended)
32	TDRT*	Device Reset Timer Period (standard)	0.600 0.600	1.125 1.125	1.85 1.95	ms ms	VDD = 5.0V (Industrial) VDD = 5.0V (Extended)
34	TIOZ	I/O High-impedance from $\overline{MCLR}$ low	—	—	2*	µs	

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 10-5: A/D CONVERTER CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
A01	NR	Resolution	—	—	8 bits	bit	
A03	EIL	Integral Error	—	—	±1.5	LSb	
A04	EDL	Differential Error	—	—	-1 < EDL ≤ + 1.5	LSb	
A05	EFS	Full-scale Range	2.0*	—	5.5*	V	
A06	EOFF	Offset Error	—	—	±1.5	LSb	
A07	EGN	Gain Error	—	—	±1.5	LSb	
A10	—	Monotonicity	—	guaranteed(1)	—	—	VSS ≤ VAIN ≤ VDD
A25	VAIN	Analog Input Voltage	VSS	—	VDD	V	
A30	ZAIN	Recommended Impedence of Analog Voltage Source	—	—	10	kΩ	
A31*	ΔIAD	A/D Conversion Current(2)	—	120	150	μA	2.0V
			—	200	250	μA	5.0V

* These parameters are characterized but not tested.

† Data in the "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only are not tested.

Note 1: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

2: This is the additional current consumed by the A/D module when it is enabled; this current adds to base IDD.

TABLE 10-6: A/D CONVERSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
AD131	TCNV	Conversion Time (not including Acquisition Time)	—	13	—	TCY	Set GO/$\overline{\text{DONE}}$ bit to new data in A/D Result register
AD132*	TACQ	Acquisition Time(1)	—	3.5 5	—	μs μs	VDD = 5V VDD = 2.5V

* These parameters are characterized but not tested.

† Data in 'Typ' column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The **Section 7.9 "A/D Acquisition Requirements"** for information on how to compute minimum acquisition times based on operating conditions.

FIGURE 11-6: MAXIMUM WDT IPD vs. VDD OVER TEMPERATURE

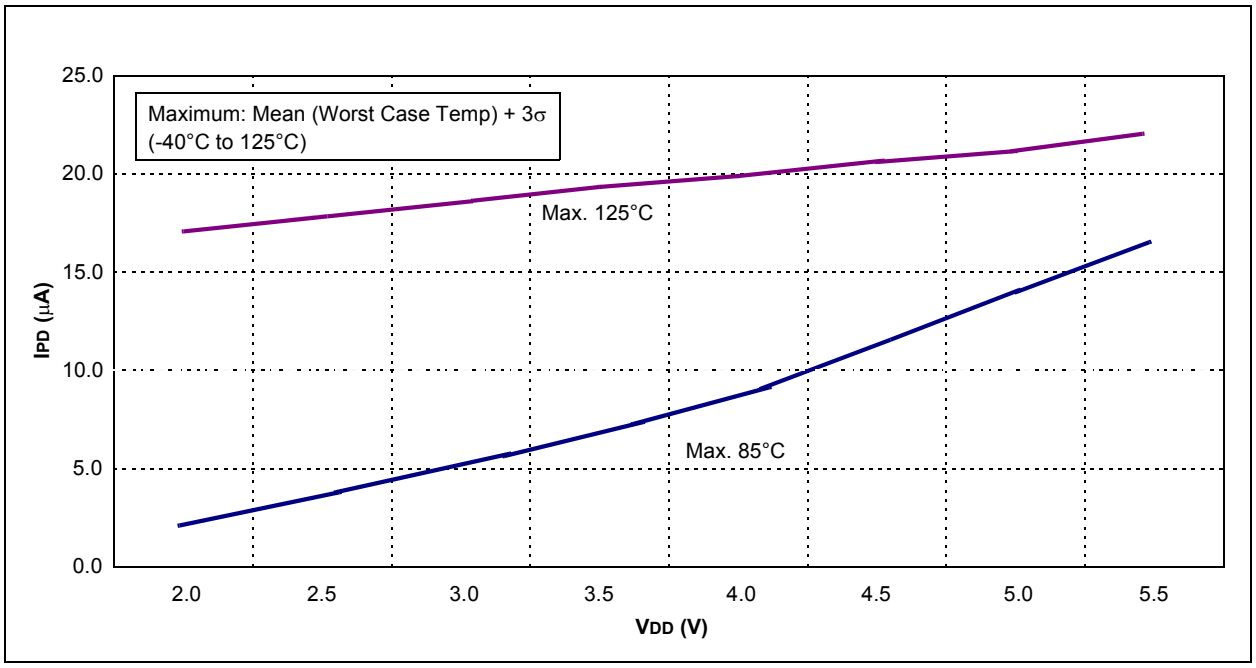


FIGURE 11-7: WDT TIME-OUT vs. VDD OVER TEMPERATURE (NO PRESCALER)

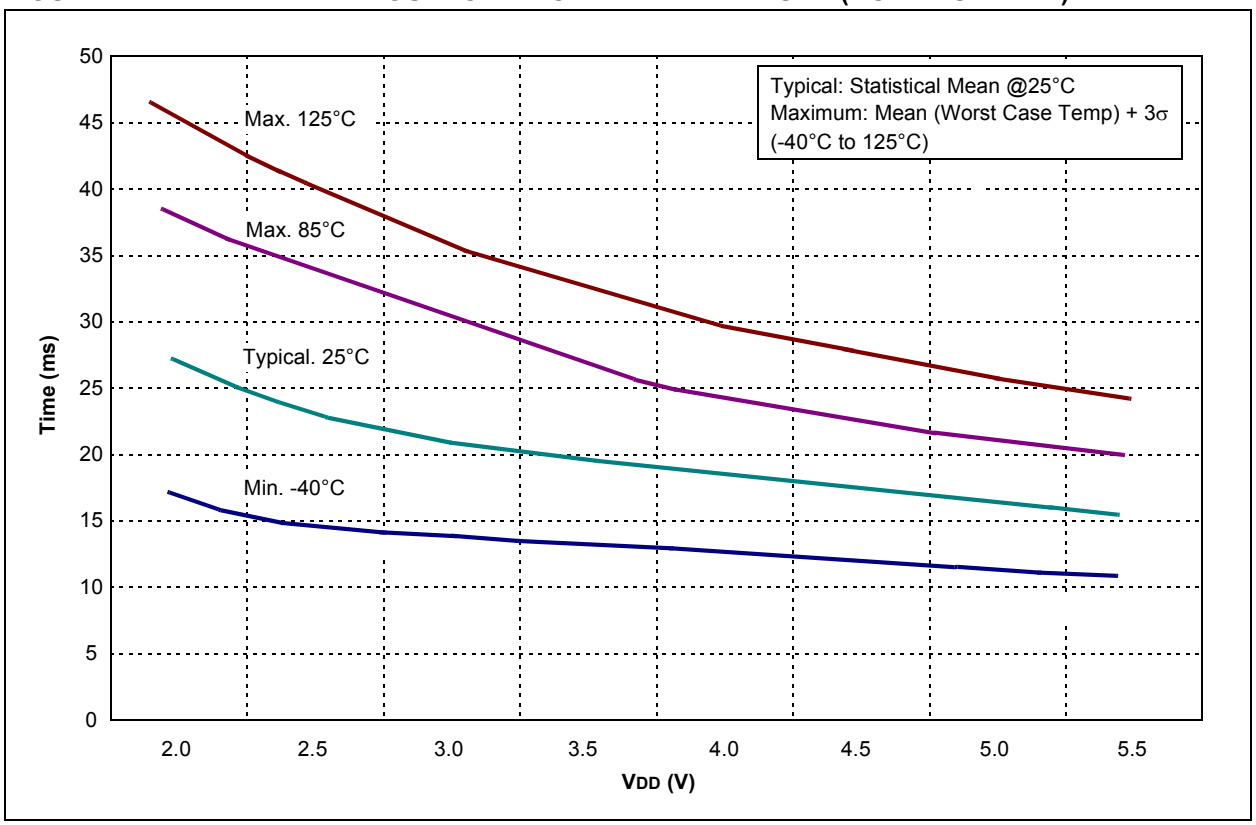


FIGURE 11-10: VOH vs. IOH OVER TEMPERATURE (VDD = 3.0V)

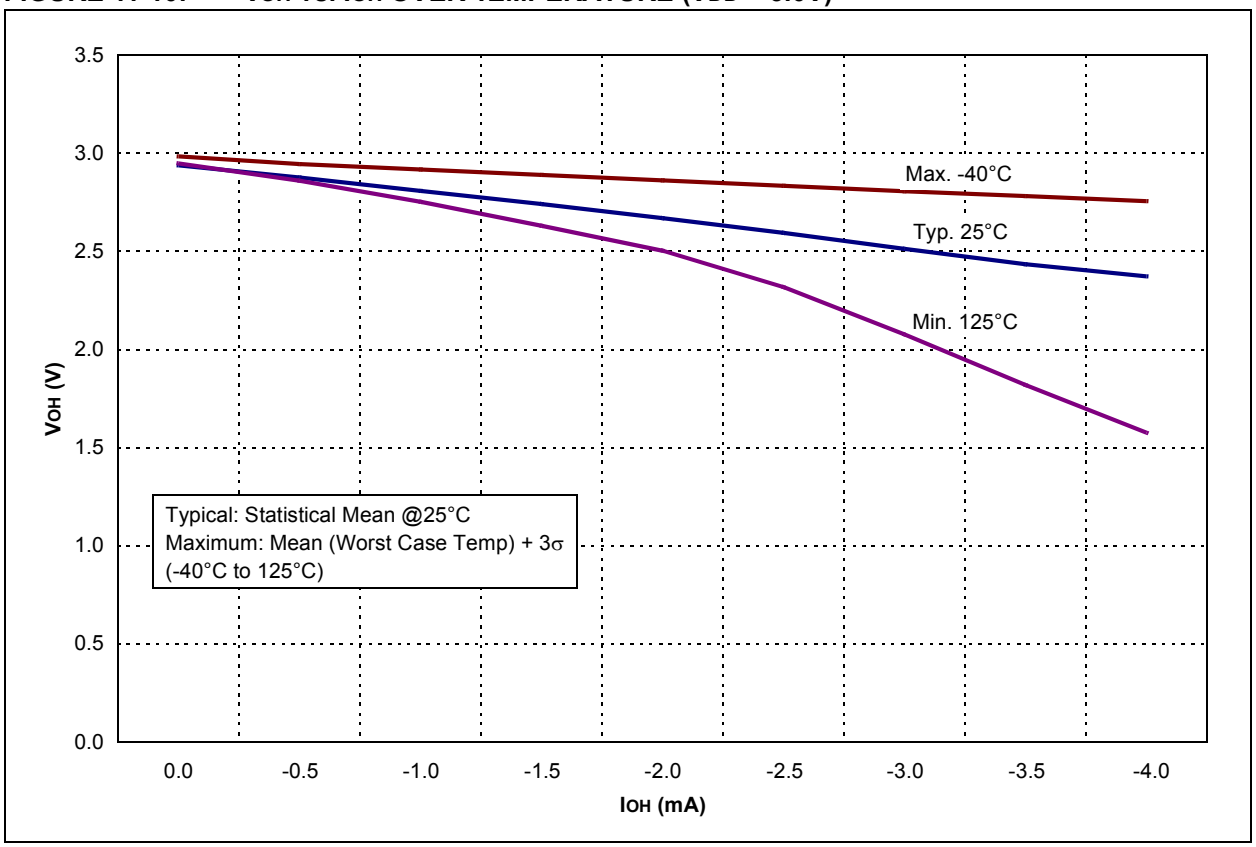


FIGURE 11-11: VOH vs. IOH OVER TEMPERATURE (VDD = 5.0V)

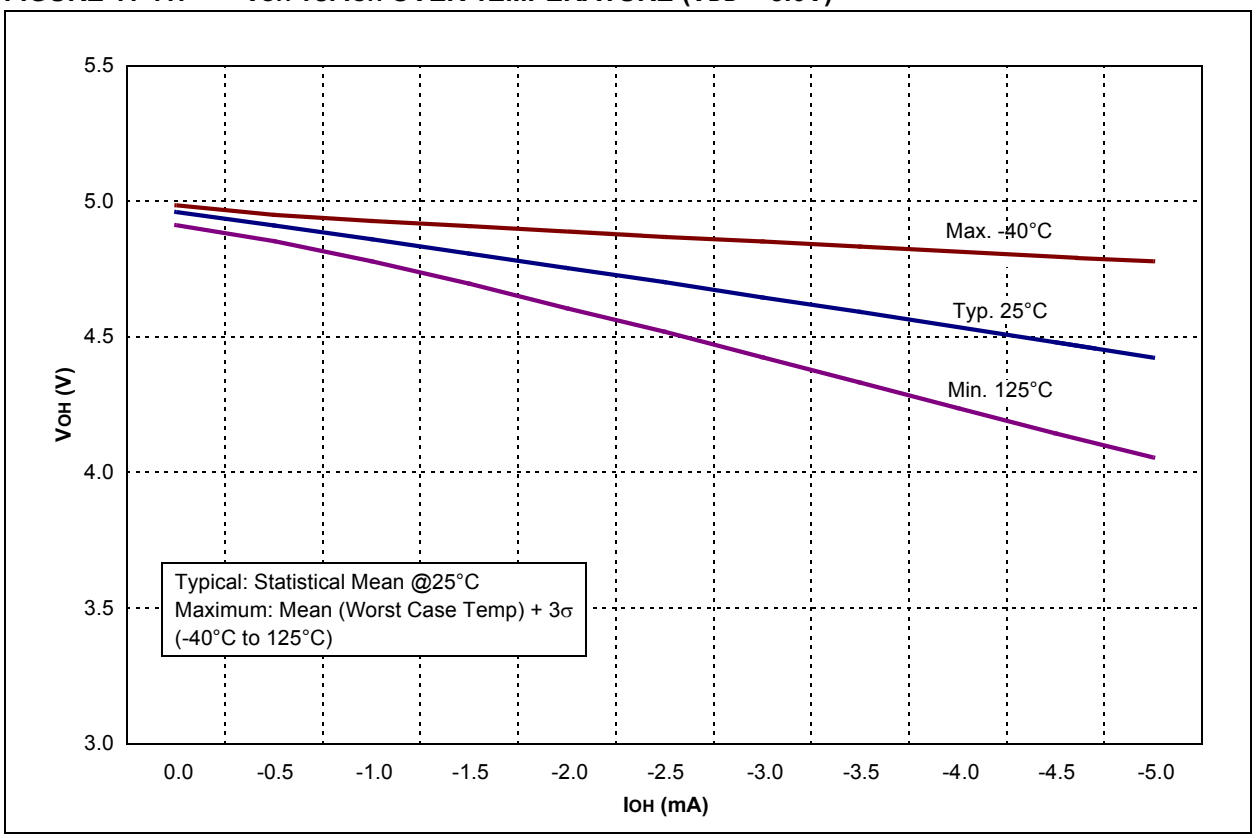


FIGURE 11-12: TTL INPUT THRESHOLD VIN vs. VDD

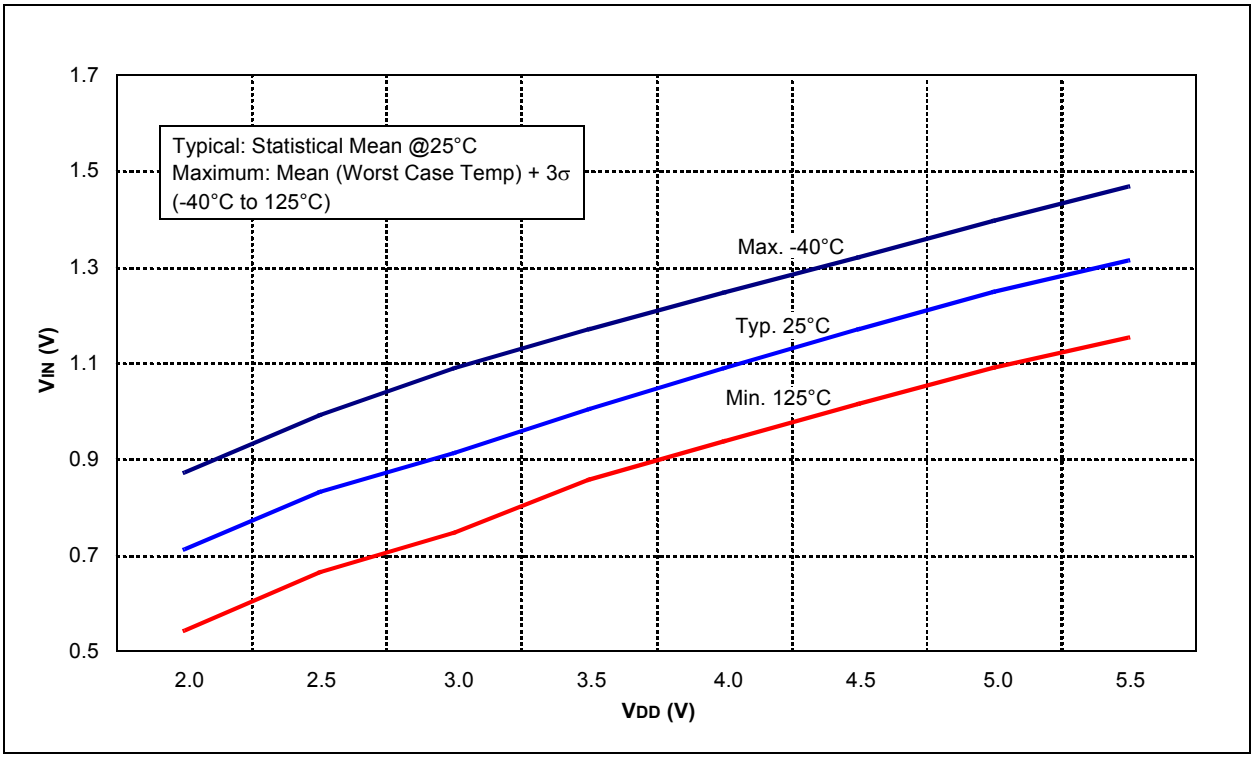
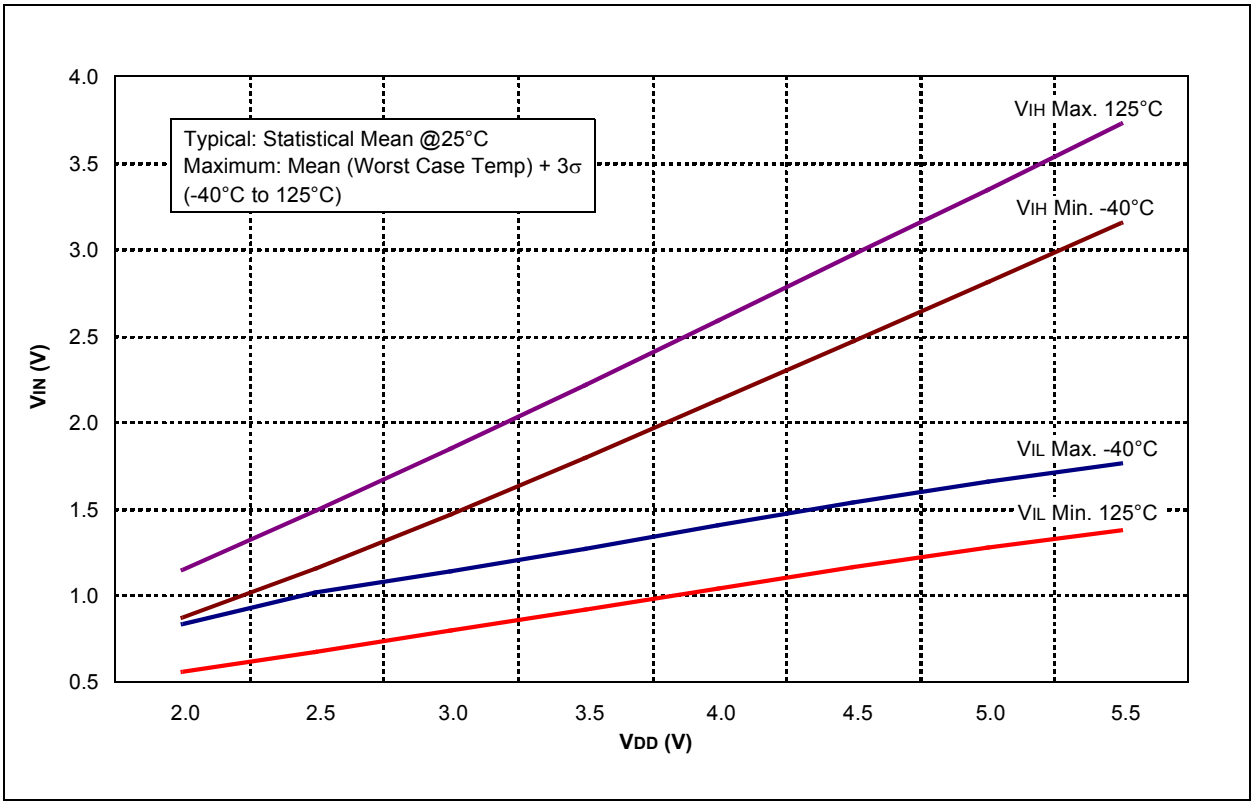


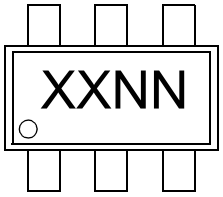
FIGURE 11-13: SCHMITT TRIGGER INPUT THRESHOLD VIN vs. VDD



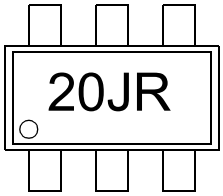
13.0 PACKAGING INFORMATION

13.1 Package Marking Information

6-Lead SOT-23*

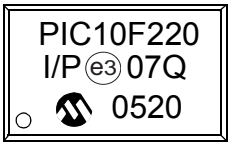


Example

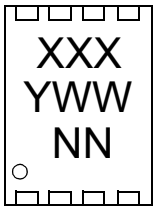


8-Lead PDIP

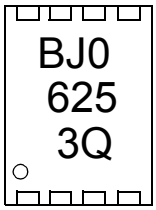
Example



8-Lead DFN*



Example

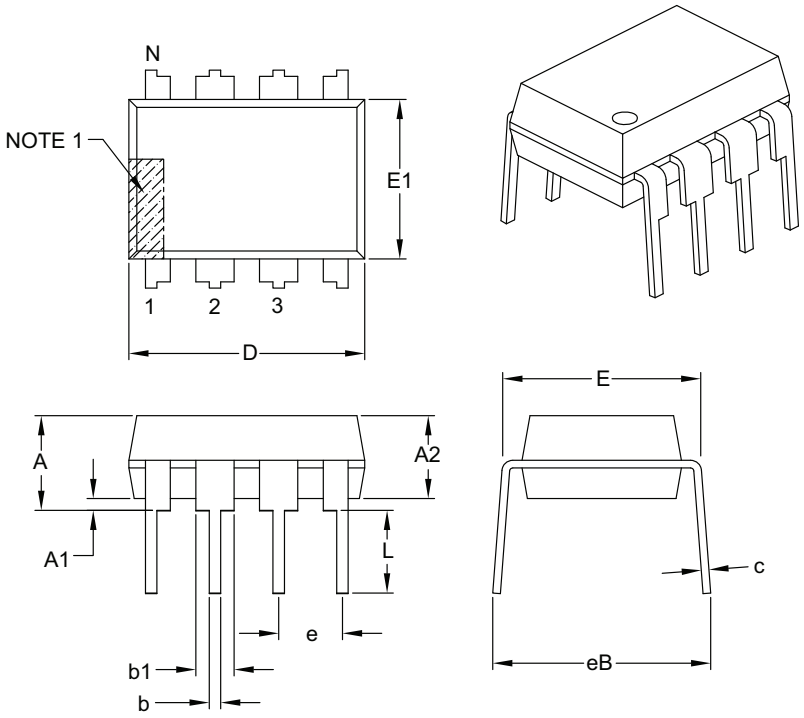


Legend:	XX...X	Product-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

8-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.348	.365	.400
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

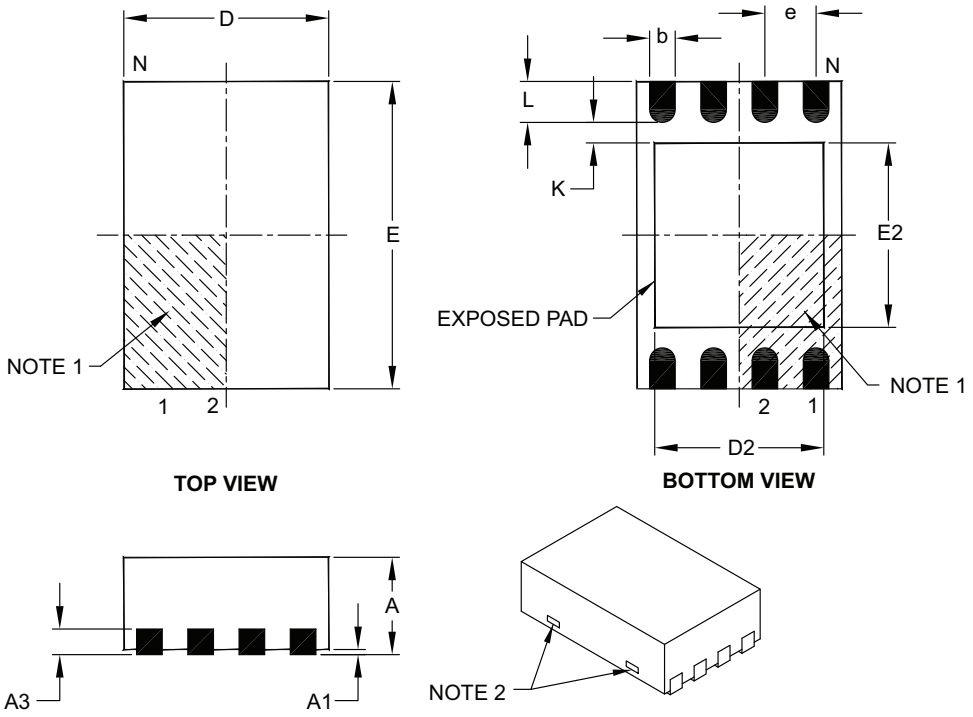
1. Pin 1 visual index feature may vary, but must be located with the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-018B

8-Lead Plastic Dual Flat, No Lead Package (MC) – 2x3x0.9 mm Body [DFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Length	D		2.00 BSC	
Overall Width	E		3.00 BSC	
Exposed Pad Length	D2	1.30	–	1.55
Exposed Pad Width	E2	1.50	–	1.75
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package may have one or more exposed tie bars at ends.
3. Package is saw singulated.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-123C

W

Z

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